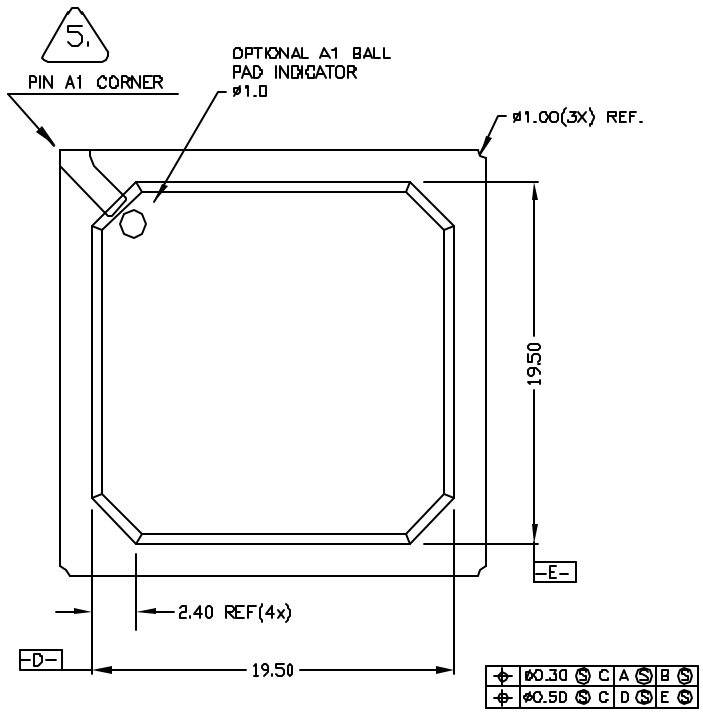
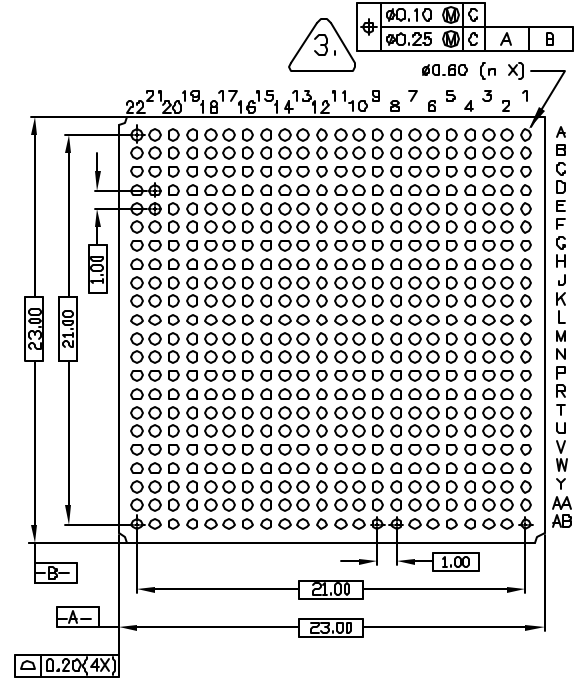


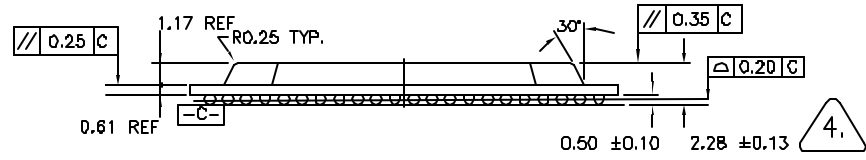
REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	09/05	
B		11/05	



TOP VIEW



BOTTOM VIEW
(BALL SIDE)



SIDE VIEW

NOTES:

1. DIMENSION IS MM.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.

3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. A1 BALL PAD CORNER I.D.

SIGNATURE		DATE		
DGC CONTROL			TITLE	
ENGR. MGR			MARKETING OUTLINE DRAWING	
MFG. ENGR			23MM X 23MM, 484 BALLS, BGA, 4 LAYER	
CHECKED BY: S. CHINNUSAMY		09/05	SIZE: A	REV. B
DRAWN BY: JFD		09/05	FSCM NO.	PART NO. 56-G6038-001
			SCALE: N/A	SHEET: 1 of 1